

SD05 and SD12 Single Line TVS Diode for ESD Protection in Portable Electronics

PROTECTION PRODUCTS

Description

The SDxx TVS diodes are designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDA's. They offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. The SDxx series TVS diodes are designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events.

The SDxx is in a SOD-323 package and will protect one unidirectional line. They are available with working voltages of 5 volts (SD05) and 12 volts (SD12). These devices will fit on the same PCB pad area as an 0805 MLV device. They give the designer the flexibility to protect one line in applications where arrays are not practical. Additionally, it may be "sprinkled" around the board in applications where board space is at a premium.

They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

Features

- ◆ 350 Watts peak pulse power (t_n = 8/20µs)
- ► Transient protection for data lines to IEC 61000-4-2 (ESD) ±25kV (air), ±10kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns) IEC 61000-4-5 (Lightning) 24A (8/20µs)
- ◆ Small package for use in portable electronics
- Suitable replacement for MLV's in ESD protection applications
- ◆ Protects one I/O or power line
- Low clamping voltage
- Working voltages: 5V and 12V
- ◆ Low leakage current
- Solid-state silicon-avalanche technology

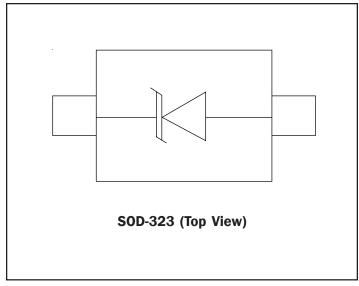
Mechanical Characteristics

- ◆ EIAJ SOD-323 package
- Molding compound flammability rating: UL 94V-0
- Marking : Marking code, cathode band
- ◆ Packaging: Tape and Reel per EIA 481

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- ◆ Portable Instrumentation
- Pagers Peripherals

Schematic & PIN Configuration





Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{pk}	350	Watts
ESD Voltage (HBM Waveform per IEC 61000-4-2)	V _{ESD}	30	kV
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature	T,	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Electrical Characteristics

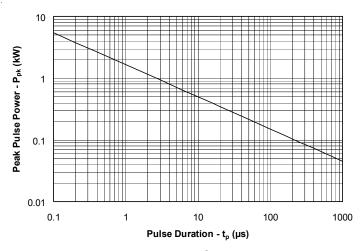
SD05						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}				5	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	6			V
Reverse Leakage Current	I _R	V _{RWM} = 5V, T=25°C			10	μA
Clamping Voltage	V _c	$I_{pp} = 5A, t_p = 8/20 \mu s$			9.8	V
Clamping Voltage	V _c	$I_{pp} = 24A, t_{p} = 8/20\mu s$			14.5	V
Peak Pulse Current	I _{PP}	t _p = 8/20μs			24	А
Junction Capacitance	C _j	V _R = OV, f = 1MHz			350	pF

SD12						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}				12	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	13.3			V
Reverse Leakage Current	I _R	V _{RWM} = 12V, T=25°C			1	μΑ
Clamping Voltage	V _c	$I_{pp} = 5A, t_p = 8/20 \mu s$			19	V
Clamping Voltage	V _c	$I_{pp} = 15A, t_{p} = 8/20\mu s$			25	V
Peak Pulse Current	I _{PP}	t _p = 8/20μs			15	А
Junction Capacitance	C _j	V _R = OV, f = 1MHz			150	pF

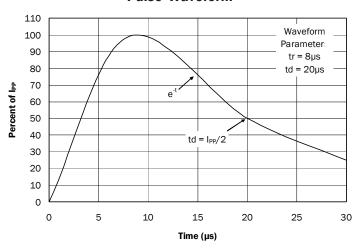


Typical Characteristics

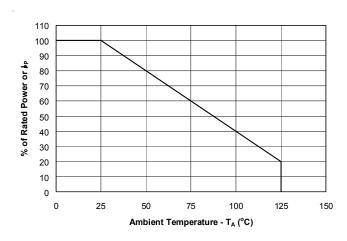
Non-Repetitive Peak Pulse Power vs. Pulse Time



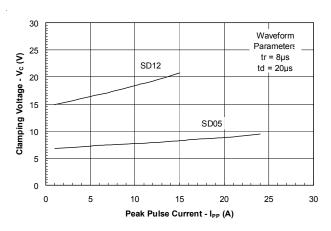
Pulse Waveform



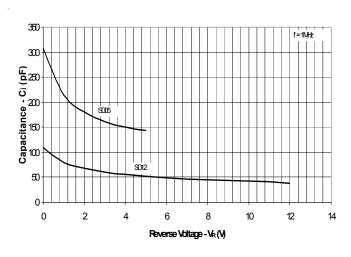
Power Derating Curve



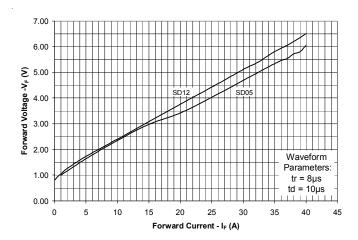
Clamping Voltage vs. Peak Pulse Current



Capacitance vs. Reverse Voltage



Forward Voltage vs. Forward Current





Applications Information

Device Connection Options

The SDxx TVS diodes are designed to protect one data, I/O, or power supply line. The device is designed to replace multi-layer varistors (MLVs) in portable applications. It is easily implemented on existing 0805 MLV pads and is only slightly larger than 0603 MLV pads. The device is unidirectional and may be used on lines where the signal polarity is above ground. The cathode band should be placed towards the line that is to be protected.

Circuit Board Layout Recommendations for Suppression of ESD.

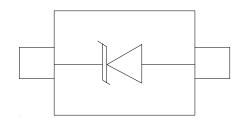
Good circuit board layout is critical for the suppression of fast rise-time transients such as ESD. The following guidelines are recommended (Refer to application note SI99-01 for more detailed information):

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- The ESD transient return path to ground should be kept as short as possible.
- Place a TVS and decoupling capacitor between power and ground of components that may be vulnerable to electrostatic discharges to the ground plane.
- Minimize all conductive loops including power and ground loops.
- Use multilaver boards when possible.
- Minimize interconnecting line lengths
- Never run critical signals near board edges.
- Fill unused portions of the PCB with ground plane.

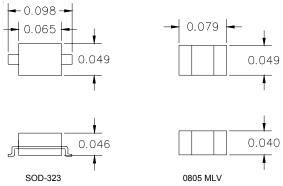
Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

Device Schematic and Pin Configuration

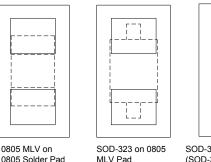


Size Comparison to 0805 MLV

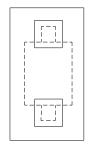


Note: Nominal dimensions in inches

Component Placement Comparison



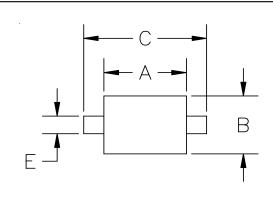
MLV Pad



SOD-323 on Recommended (SOD-323) Solder Pad

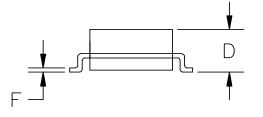


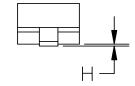
Outline Drawing



DIM	INCHES		M	NOTE	
ואוטן	MIN	MAX	MIN	MAX	NOIL
Α	.060	.071	1.5	1.8	_
В	.045	.054	1.2	1.4	_
С	.090	.107	2.3	2.7	_
D	_	.043	_	1.1	_
E	.012	.016	0.3	0.4	_
F	.004	.010	.10	.25	_
Н	_	.004	_	.10	_
	•		•	•	•

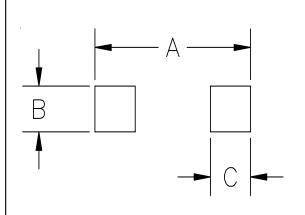
DIMENSIONS





1 CONTROLLING DIMENSION: MILLIMETERS

Land Pattern



DIMENSIONS						
DIM		HES		M 1	NOTE	
וויוט	MIN	MAX	MIN	MAX	NOIL	
Α		.120		3.05		
В	_	.031	-	8.0		
C	_	.031	_	0.8	_	

1 CONTROLLING DIMENSION: MILLIMETERS



Marking Codes

Part Number	Marking Code		
SD05	5U		
SD12	6U		

Ordering Information

Part Number	Lead Finish	Qty per Reel	Reel Size
SD05.TC	SnPb	3,000	7"
SD12.TC	SnPb	3,000	7"
SD05.TCT	Pb free	3,000	7"
SD12.TCT	Pb free	3,000	7"

Contact Information

Semtech Corporation Protection Products Division 200 Flynn Rd., Camarillo, CA 93012 Phone: (805)498-2111 FAX (805)498-3804

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P6KE8.2A SA110CA SA60CA SA64CA SMBJ12CATR SMBJ8.0A SMLJ30CA-TP ESD101-B1-02ELS E6327 ESD112-B1-02EL E6327
ESD119B1W01005E6327XTSA1 ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF 3.0SMCJ33CA-F
3.0SMCJ36A-F HSPC16701B02TP D3V3Q1B2DLP3-7 D55V0M1B2WS-7 DESD5V0U1BL-7B DRTR5V0U4SL-7 SCM1293A-04SO
ESD200-B1-CSP0201 E6327 ESD203-B1-02EL E6327 SM12-7 SMF8.0A-TP SMLJ45CA-TP CEN955 W/DATA 82350120560
82356240030 VESD12A1A-HD1-GS08 CPDUR5V0R-HF CPDUR24V-HF CPDQC5V0U-HF CPDQC5V0USP-HF CPDQC5V0-HF
D1213A-01LP4-7B D1213A-02WL-7 ESDLIN1524BJ-HQ 5KP100A 5KP15A